- **Members of the Texas Instruments** Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- **Independent Registers for A and B Buses**
- **Multiplexed Real-Time and Stored Data**
- Flow-Through Architecture Optimizes **PCB Layout**
- Distributed V<sub>CC</sub> and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- **EPIC™** (Enhanced-Performance Implanted CMOS) 1-um Process
- 500-mA Typical Latch-Up Immunity at
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center **Pin Spacings**

### description

The 'ACT16646 are 16-bit bus transceivers consisting of D-type flip-flops and control circuitry with 3-state outputs arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The devices can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental busmanagement functions that can be performed with the bus transceivers and registers.

**54ACT16646...WD PACKAGE** 74ACT16646...DL PACKAGE (TOP VIEW)

1				ì
1DIR [	1	$\cup$	56	] 1 <u>OE</u>
1CLKAB [	2		55	] 1CLKBA
1SAB [	3		54	] 1SBA
GND [	4		53	] GND
1A1 [	5		52	] 1B1
1A2 [	6		51	] 1B2
V <sub>CC</sub> [	7		50	] v <sub>cc</sub>
1A3 [	8		49	] 1B3
1A4 [	9		48	] 1B4
1A5 [	10		47	] 1B5
GND [	11		46	] GND
1A6 [	12		45	] 1B6
1A7 [	13		44	] 1B7
1A8 [	14		43	] 1B8
2A1 [	15		42	] 2B1
2A2 [	16		41	] 2B2
2A3 [	17		40	] 2B3
GND [	18		39	] GND
2A4 [	19		38	] 2B4
2A5 [	20		37	] 2B5
2A6 [	21		36	] 2B6
V <sub>CC</sub> [	22		35	] v <sub>cc</sub>
2A7 [	23		34	] 2B7
2A8 [	24		33	] 2B8
GND [	25		32	] GND
2SAB [	26		31	2SBA
2CLKAB	27		30	2CLKBA
2DIR [	28		29	] 2 <mark>0E</mark>
	_			,

Output-enable (OE) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select controls (SAB and SBA) can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. DIR determines which bus receives data when  $\overline{\mathsf{OE}}$  is low. In the isolation mode ( $\overline{\mathsf{OE}}$ high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

The 74ACT16646 is packaged in TI's shrink small-outline package, which provides twice the functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16646 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT16646 is characterized for operation from -40°C to 85°C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.



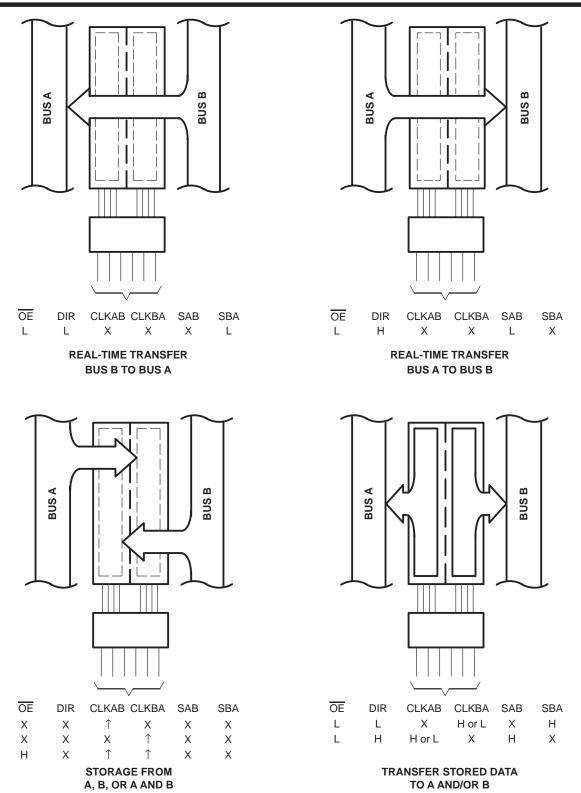


Figure 1. Bus-Management Functions



# 54ACT16646, 74ACT16646 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCAS127B - MARCH 1990 - REVISED APRIL 1996

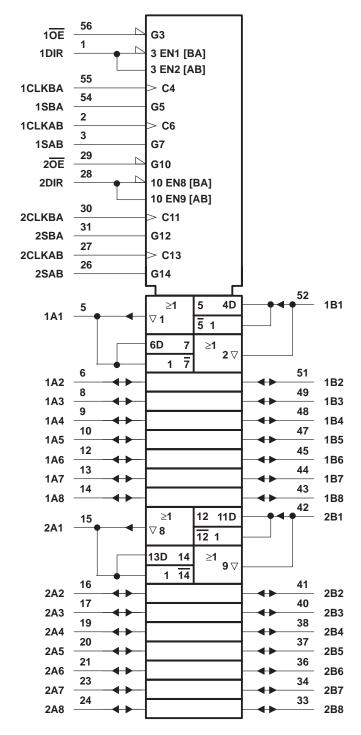
#### **FUNCTION TABLE**

		INP	UTS			DATA	\ I/O†	OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified	Store A, B unspecified <sup>†</sup>
X	Χ	Χ	1	Χ	Χ	Unspecified	Input	Store B, A unspecified <sup>†</sup>
Н	Х	1	1	Χ	Х	Input	Input	Store A and B data
Н	Χ	H or L	H or L	Χ	Χ	Input	Input	Isolation, hold storage
L	L	Х	Χ	Χ	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B Bus
L	Н	H or L	X	Н	X	Input	Output	Stored A data to bus

<sup>†</sup> The data-output functions may be enabled or disabled by various signals at OE or DIR. Data-input functions are always enabled, i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



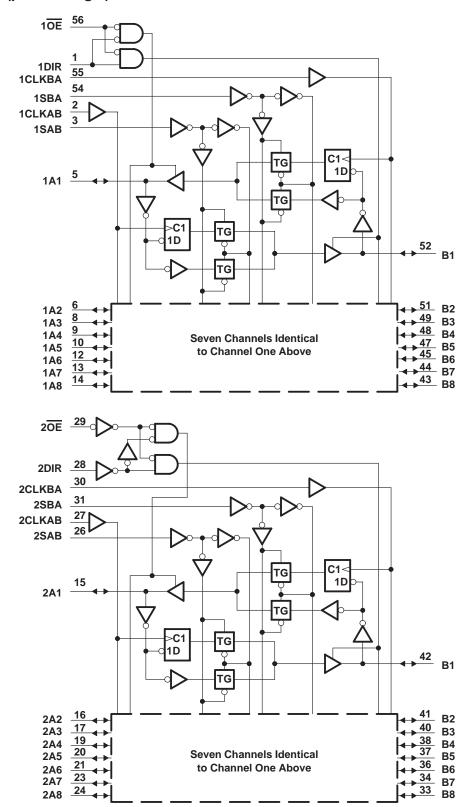
# logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



# logic diagram (positive logic)





# 54ACT16646, 74ACT16646 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCAS127B - MARCH 1990 - REVISED APRIL 1996

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$-0.5 \ V$ to $7 \ V$
Input voltage range, V <sub>I</sub> (see Note 1)	5 V to V <sub>CC</sub> + 0.5 V
Output voltage range, V <sub>O</sub> (see Note 1)–0.	5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	$\dots \dots \pm 20 \text{ mA}$
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±400 mA
Maximum package power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T <sub>Stg</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## recommended operating conditions (see Note 3)

		54ACT	16646	74ACT	16646	UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage (see Note 4)	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	3	2		V
VIL	Low-level input voltage		0.8		0.8	V
٧ <sub>I</sub>	Input voltage	0	Vcc	0	VCC	V
VO	Output voltage	0	Vcc	0	VCC	V
IOH	High-level output current	2	-24		-24	mA
loL	Low-level output current	30/	24		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	0	10	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTES: 3. Unused inputs must be held high or low to prevent them from floating.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

<sup>4.</sup> All V<sub>CC</sub> and GND pins must be connected to the proper voltage power supply.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA.	RAMETER	TEST CONDITIONS	V	T,	<sub>Δ</sub> = 25°C		54ACT	16646	74ACT	16646	UNIT
PAI	RAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		I <sub>OH</sub> = -50 μA	4.5 V	4.4			4.4		4.4		
		ΙΟΗ = -30 μΑ	5.5 V	5.4			5.4		5.4		
		I <sub>OH</sub> = -24 mA	4.5 V	3.94			3.7		3.8		V
VOH		10H = -24 IIIA	5.5 V	4.94			4.7		4.8		V
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85				
		I <sub>OH</sub> = -75 mA <sup>†</sup>	5.5 V						3.85		
		15. – 50A	4.5 V			0.1		0.1		0.1	
		I <sub>OL</sub> = 50 μA	5.5 V			0.1		0.1		0.1	
<b> </b>		lo 24 mA	4.5 V			0.36		0.5		0.44	V
VOL		I <sub>OL</sub> = 24 mA	5.5 V			0.36	S,	0.5		0.44	V
		I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V				90	1.65			
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V				Ya			1.65	
Ц	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			±0.1		±1		±1	μΑ
loz	A or B ports <sup>‡</sup>	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μΑ
Icc	_	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		160		80	μА
ΔICC§		One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V			0.9		1		1	mA
Ci	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4						pF
C <sub>io</sub>	A or B ports	$V_O = V_{CC}$ or GND	5 V		12						pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature, (unless otherwise noted) (see Figure 2)

			T <sub>A</sub> = 2	25°C	54ACT	16646	74ACT	16646	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	90	0	90	0	90	MHz
t <sub>W</sub>	Pulse duration, CLKAB or CLKBA high or low	CLKAB or CLKBA high or low				10,7	5.5		ns
	Octor for Abeter OlivaPher Bheter OlivaPh	Data high	4		4		4		no
t <sub>su</sub>	Setup time, A before CLKAB↑ or B before CLKBA↑	Data low	6		6		6		ns
th	Hold time, A before CLKAB↑ or B before CLKBA↑	CLKAB↑ or B before CLKBA↑					1.5		ns

<sup>‡</sup> For I/O ports, the parameter IOZ includes the input leakage current.

<sup>§</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

# 54ACT16646, 74ACT16646 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCAS127B - MARCH 1990 - REVISED APRIL 1996

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	Т,	Δ = 25°C	;	54ACT	16646	74ACT	16646	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
f <sub>max</sub>			90			90		90		MHz
<sup>t</sup> PLH	A or B	B or A	3.9	7.5	9.4	3.9	11.5	3.9	10.6	ns
t <sub>PHL</sub>	AOIB	BOIA	3.4	7.6	10.6	3.4	12.2	3.4	11.4	115
<sup>t</sup> PZH	ŌĒ	A or B	3.2	7.7	10.8	3.2	12.9	3.2	11.9	ns
t <sub>PZL</sub>	OE	AOIB	4.2	9	12.2	4.2	14.6	4.2	13.5	115
<sup>t</sup> PHZ	ŌĒ	A or B	5.3	7.7	9.6	5.3	10.4	5.3	10.2	ns
tPLZL	OE	AOIB	4.9	7.3	9.2	4.9	10.3	4.9	9.9	115
<sup>t</sup> PLH	CLKBA or CLKAB	A or B	4.9	8.9	11.1	4.9	13.1	4.9	12.2	ns
t <sub>PHL</sub>	CLNBA OI CLNAB	AUIB	5.1	9	11	5.1	13.1	5.1	12.3	115
<sup>t</sup> PLH	SAB or SBA <sup>†</sup>	A or B	5.2	10.3	13.8	5.2	17.2	5.2	15.6	ns
<sup>t</sup> PHL	(with A or B high)	AOIB	4.9	8.2	10.6	4.9	12.5	4.9	11.7	115
t <sub>PLH</sub>	SBA or SAB <sup>†</sup>	A or B	4.3	7.8	9.9	4.3	12.1	4.3	11.1	ns
<sup>t</sup> PHL	(with A or B high)	AOIB	5.9	11.2	14.9	5.9	18.2	5.9	16.7	115
<sup>t</sup> PZH	DIR	A or B	4.5	9.5	13.6	4.5	16.2	4.5	15.2	ns
<sup>t</sup> PZL	DIK	A or B	4.3	9.2	11.8	4.3	14.2	4.3	13.1	115
t <sub>PHZ</sub>	DIR	A or B	4.5	7.9	10.2	4.5	11.2	4.5	10.8	ns
t <sub>PLZ</sub>	DIK	AUID	4.4	7.5	9.8	4.4	10.8	4.4	10.4	119

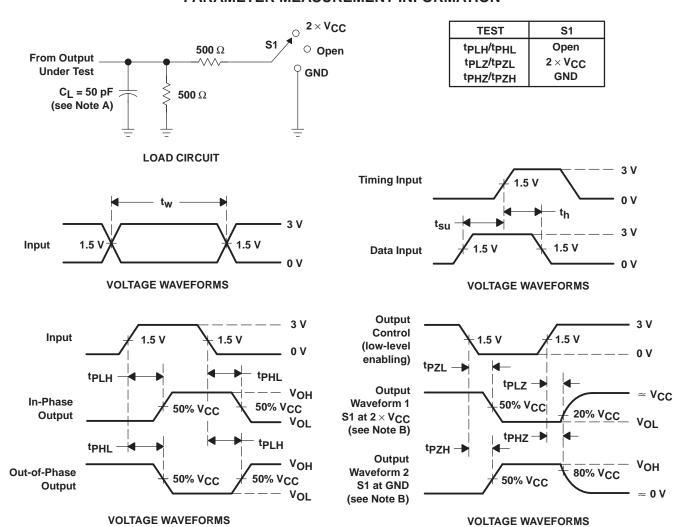
<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

# operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER		TEST CO	TYP	UNIT	
C .	Power dissipation capacitance per transceiver	Outputs enabled	$C_1 = 50 pF$	f = 1 MHz	58	nE.
Cpd	rower dissipation capacitance per transcerver	Outputs disabled	CL = 50 pr,	I = I IVIIIZ	13	p⊦



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_{\rm O} = 50~\Omega$ ,  $t_{\rm f} = 3~{\rm ns}$ ,  $t_{\rm f} = 3~{\rm ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

www.ti.com 13-Aug-2021

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
74ACT16646DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16646	Samples
74ACT16646DLR	ACTIVE	SSOP	DL	56	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16646	Samples
74ACT16646DLRG4	ACTIVE	SSOP	DL	56	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16646	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



# **PACKAGE OPTION ADDENDUM**

www.ti.com 13-Aug-2021

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 5-Jan-2022

## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16646DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

www.ti.com 5-Jan-2022



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16646DLR	SSOP	DL	56	1000	367.0	367.0	55.0

# PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

## **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74ACT16646DL	DL	SSOP	56	20	473.7	14.24	5110	7.87

# DL (R-PDSO-G56)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated